

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
AKIHISA NAKANO	06/04/2018
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	KAIJO CORPORATION
<b>Street Address:</b>	3-1-5, SAKAE-CHO, HAMURA-SHI
<b>City:</b>	TOKYO
<b>State/Country:</b>	JAPAN
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	29650549
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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<b>NAME OF SUBMITTER:</b>	KAZUTO ISHIHARA
<b>SIGNATURE:</b>	/Kazuto Ishihara/
<b>DATE SIGNED:</b>	06/07/2018
<b>Total Attachments: 1</b>	
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## ASSIGNMENT

For good and valuable consideration received of the hereinafter named assignee(s), receipt of which is hereby acknowledged, I, the undersigned, Akihisa NAKANO, hereby sell and assign to KAIJO CORPORATION, a corporation of the country of Japan and having a place of business at 3-1-5, Sakae-cho, Hamura-shi, Tokyo, Japan, assignee's successors and assigns, the entire right, title and interest, so far as concerns the United States and the Territories and Possessions thereof and all foreign countries, in and to the inventions in

### ULTRASONIC TRANSDUCER

set forth in the application for United States Letters Patent executed by the undersigned on the respective dates set forth below, said application for United States Letters Patent, any and all other applications for Letters Patent on said inventions in countries foreign to the United States, including all divisional, renewal, substitute, continuation and Convention applications based in whole or in part upon said inventions or upon said applications, and any and all Letters Patent and reissues and extension of Letters Patent granted for said inventions or upon said applications, and every priority right that is or may be predicated upon or arise from said inventions, said applications and said Letters Patent; said assignee being hereby authorized to file patent applications in any or all countries on any or all said inventions in the name of the undersigned or in the name of said assignee or otherwise as said assignee may deem advisable, under the International Convention or otherwise; the Commissioner of Patents of the United States of America and the empowered officials of all other governments being hereby authorized to issue or transfer all said Letters Patent to said assignee in accordance herewith; this assignment being under covenant, not only that full power to make the same is had by the undersigned, but also that such assigned right is not encumbered by any grant, license, or other right heretofore given, and that the undersigned will do all acts reasonably serving to assure that the said inventions, patent applications and Letters Patent shall be held and enjoyed by said assignee as fully and entirely as the same could have been held and enjoyed by the undersigned if this assignment had not been made, and particularly to execute and deliver to said assignee all lawful documents including petitions, specifications, oaths, assignments, invention disclaimers, and lawful affidavits in form and substance which may be requested by said assignee, to furnish said assignee with all facts relating to said inventions or the history thereof and any and all documents, photographs, models, samples or other physical exhibits which may be useful for establishing the facts of conception, disclosure and reduction to practice of said inventions, and to testify in any proceedings relating to said inventions, patent applications and Letters Patent.

Signed:

Dated:

Akihisa Nakano.  
Akihisa NAKANO

June. 4. 2018